IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
In re application of: Tien-Jen Cheng	Filed: 07/31/2003 Examiner: Nathan Ha
Serial No. 10/604,378 10 604,578	
Title: Encapsulated Pin Structure for Improved Reliability of Wafer	<u>Docket #:</u> FIS920030103US1

AMENDMENT

Commissioner of Patents & Trademarks Alexandria, VA 22313

Sir:

Responsive to the Restriction Requirement of 07/25/2005, please amend the above identified application as follows: